

Product Change Notification - JAON-29SXBX512

Date: 10 Jan 2018

Product Category: Depletion Mode MOSFETs; Insulated Gate Bipolar Transistors; N-Channel Enhancement Mode MOSFETs

Notification subject: CCB 2773 Final Notice: Qualification of GTBF assembly site for selected Supertex products available in 3L DPAK package using 8060T die attach material.

Notification text: **PCN Status:**
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of GTBF assembly site for selected Supertex products available in 3L DPAK package using 8060T die attach material.

Pre Change:

Assembled at GEMC assembly site using 84-1LMISR4 die attach material

Post Change:

Assembled at GTBF assembly site using 8060T die attach material

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	GEM Electronics (Shanghai) Co., Ltd. (GEMC)	Great Team Backend Foundry (Dong Guan) Ltd. (GTBF)
Wire material	Au wire	Au wire
Die attach material	84-1LMISR4	8060T
Molding compound material	G600	G600
Lead frame material	PMC90	PMC90

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying GTBF assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

February 10, 2018 (date code: 1806)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	December 2016					->	January 2018				February 2018			
	48	49	50	51	52		01	02	03	04	05	06	07	08
Initial PCN Issue Date		X												
Qual Report Availability							X							
Final PCN Issue Date							X							
Estimated Implementation Date											X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:

December 6, 2016: Issued initial notification.

January 10, 2018: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 9, 2018.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

[PCN_JAON-29SXBX512_Affected_CPN.pdf](#)

[PCN_JAON-29SXBX512_Qual_Report.pdf](#)

[PCN_JAON-29SXBX512_Affected_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_JAON-29SXBX512
CATALOG_PART_NBR
DN2450K4-G
DN2470K4-G
DN2625K4-G
DN3765K4-G
GN2470K4-G
TN2640K4-G